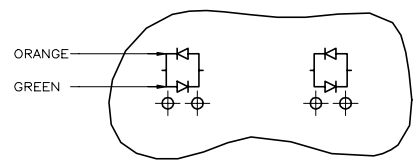
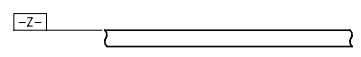
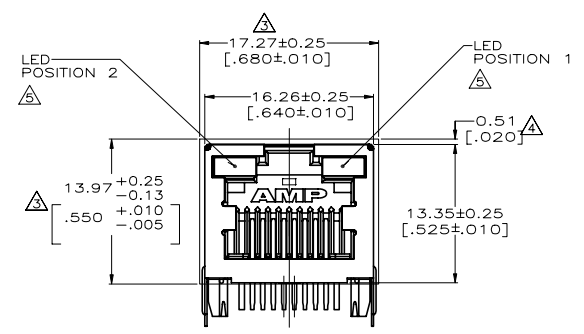
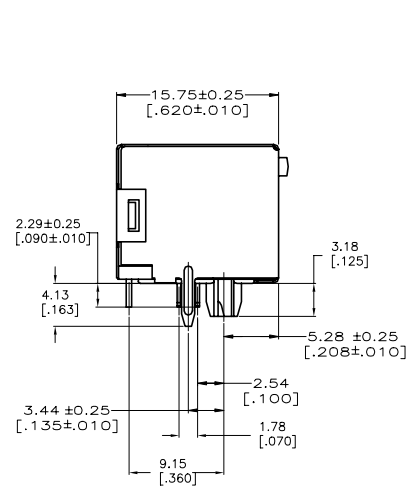
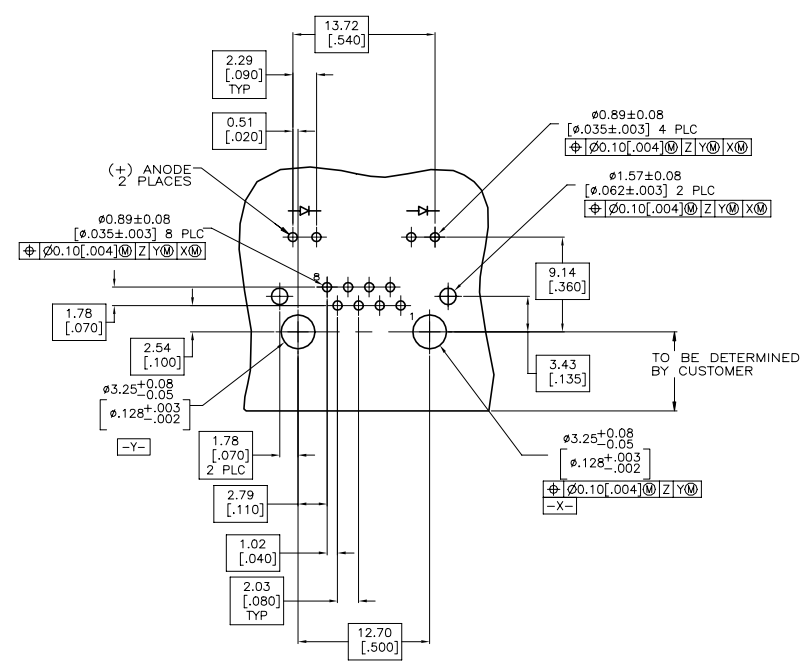


| REVISIONS | | | | |
|-----------|-----------|---------------|----|-------|
| REV | DATE | DESCRIPTION | BY | APP'D |
| F4 | 29AUG2020 | ECO-18-014918 | RR | SH |



LED CURRENT DIAGRAM
1116075-7 ONLY



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC,
COLOR: BLACK, UL94V-0
TERMINALS - 0.36[.014] THICK PHOS BRONZE
PLATED WITH 3.81µm[.000150] MIN THICK
BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050]
MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE
TERMINAL PLATED WITH 1.27µm[.000050] MIN
THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY
PREPLATED WITH 1.27µm[.000050] MIN SATIN
NICKEL WITH 2.03µm[.000080] MIN TIN POST
DIPPED ON PCB GROUND TABS
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY
LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL
WIREFRAME LEADS PLATED WITH 8.89µm[.000350]
TIN/COPPER OVER 2.03µm[.000080] SILVER OVER
1.02µm[.000040] NICKEL UNDERPLATE OVER
2.03µm[.000080] COPPER UNDERPLATE
 - JACK CAVITY CONFORMS TO FCC RULES AND
REGULATIONS PART 68, SUBPART F.
- △ RECOMMENDED PANEL OPENING DIMENSIONS.
 - △ RECOMMENDED CLEARANCE BETWEEN TOP OF CONNECTOR
AND TOP PANEL OPENING.
 - △ SEE TABLE FOR COLOR OF LEDS AND NUMBER
REQUIRED.
 - 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT
IR REFLOW SOLDERING PROCESS COMPATIBLE.
 - △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

| INDICATOR COLOR | POSITION 2 | POSITION 1 | PART NUMBER |
|-----------------|--------------|--------------|-------------|
| OBsolete | YELLOW/GREEN | YELLOW/GREEN | -1116075-8- |
| OBsolete | ORANGE/GREEN | ORANGE/GREEN | -1116075-7- |
| OBsolete | YELLOW | YELLOW | -1116075-6- |
| OBsolete | GREEN | GREEN | -1116075-5- |
| OBsolete | GREEN | YELLOW | -1116075-4- |
| △ OBsolete | YELLOW | - | -1116075-3- |
| OBsolete | - | GREEN | -1116075-2- |
| SUPERSEDED | YELLOW | GREEN | -1116075-1- |

THIS DRAWING IS A CONTROLLED DOCUMENT.

| | | | |
|------------------------|------------------------------|------------------|-------------------|
| DATE: 11-14-2014 | REV: 1 | BY: M. DESTINE | CHKD: M. DESTINE |
| APPROVED: M. DESTINE | DATE: 11-14-2014 | BY: M. DESTINE | CHKD: M. DESTINE |
| PRODUCT SPEC: 114-2154 | APPLICATION SPEC: 108-1163-4 | SIZE: A1 | SCALE: 4:1 |
| MATERIAL: SEE NOTE 1 | FINISH: SEE NOTE 1 | WEIGHT: 0.000000 | RESTRICTED TO: F4 |

TE Connectivity
INVERTED MODULAR JACK ASSEMBLY,
1X1, SHIELDED, LED

108-1163-4
00779
1116075